



AMENDMENT TRANSMITTAL LETTER

Docket No.
ROH-0049

Application No.
10/091,544

Filing Date
March 7, 2002

Examiner
L. Thai

Art Unit
2827

Applicant(s): Kazutaka SHIBATA

Invention: SEMICONDUCTOR DEVICE HAVING A WARP PREVENTING SHEET

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	8	- 20 =		x	0.00
Independent Claims	2	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

☒ Large Entity

☐ Small Entity

☒ No additional fee is required for this amendment.

☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.

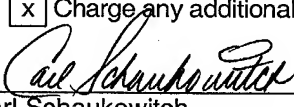
☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.

☐ Payment by credit card. Form PTO-2038 is attached.

☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 18-0013
as described below. A duplicate copy of this sheet is enclosed.

☒ Credit any overpayment.

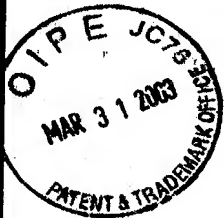
☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.


Carl Schaukowitch
Attorney Reg. No.: 29,211

Dated: March 31, 2003

RADER, FISHMAN & GRAUER PLLC
1233 20th Street, N.W.
Suite 501
Washington, DC 20036
(202) 955-3750

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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Kazutaka SHIBATA

Application No.: 10/091,544

Filed: March 7, 2002

For: SEMICONDUCTOR DEVICE HAVING A WARP PREVENTING SHEET

Attorney Docket No.: ROH-0049

Examiner: L. Thai

Art Unit: 2827

Confirmation No.: 9071

AMENDMENT UNDER 37 C.F.R. §1.111

BOX NON-FEE AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

In response to the Office Action dated January 3, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 1 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), the amended claim(s) are set forth in a marked-up version in the page(s) attached to this Amendment.

1. (Amended) A semiconductor device comprising:
 - a substrate;
 - a semiconductor chip having one surface bonded to a surface of the substrate; and
 - a warp preventing sheet bonded to and entirely covering the other surface of the semiconductor chip, wherein
 - end surfaces of the warp preventing sheet are flush with corresponding end surfaces of the semiconductor chip.

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